

PA-248342

ECD Product Advisory - Expanding to Foxconn Vietnam Manufacturing Site for Emulex FC HBAs

Issue Date: 5/20/2022

Change Description:

Expanding to add a larger facility within Foxconn Vietnam campus to increase production capacity.

Parts Affected:

All Emulex Gen6 16GFC and 32GFC (Lancer G6-based) HBAs:

- LPe31000-series (Gen6 16GFC) – All Emulex-branded and corresponding OEM derivative and custom HBAs
- LPe32000-series (Gen6 32GFC) – All Emulex-branded and corresponding OEM derivative and custom HBAs

All Emulex Gen7 32GFC and 64GFC (Prism-based) HBAs:

- LPe35000-series (Gen7 32GFC) – All Emulex-branded and corresponding OEM derivative and custom HBAs
- LPe36000-series (Gen7 64GFC) – All Emulex-branded and corresponding OEM derivative and custom HBAs

Description and Extent of Change:

Per PA-238149 dated 9/21/21; Broadcom Emulex Connectivity Division expanded their manufacturing to add Foxconn Vietnam due to increase in demand and to ensure continuity of supply. Broadcom manufacturing demands have since increased, necessitating the move to a location that facilitates increased capacity. Other Broadcom BU's have already qualified the Bac Giang site.

The CM location is traceable through the board serial number. The letters "FG" at the prefix of the serial number indicates a Foxconn Bac Giang Vietnam manufactured board product. Below is an illustrative board label example and the factory address for Foxconn Bac Giang Vietnam:



Lot M1 & Lot F, Quang Chau Industrial Park, Van Trung Commune

Viet Yen District, Bac Giang Province, 35000 Vietnam

Reasons for Change:

Emulex Connectivity Division (ECD) is proactively expanding the manufacturing supplier base for FC HBAs to safeguard availability. Foxconn Bac Giang Vietnam is already an approved Broadcom manufacturing site and has met all required quality control processes and is a manufacturing supplier for other Broadcom board-level products.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

- No form/fit/functional hardware changes to the PCB or PCBA
- HBA functional and performance specifications remain the same

Recommended Action by the Customer:

- Acknowledge this Product Advisory and ensure your respective Receiving Inspection departments are prepared to receive products from Foxconn Vietnam
- For OEM products, if a new site code is required for customer labeling to indicate assembly location, please work with your Broadcom ECD contacts to update custom labels as needed

Effective Date of Change:

Product shipments using this change will begin after September 1st, 2022. Timing of shipment of the board products will vary by part number depending on customer demand and inventory levels.

Qualification Data:

- Electronic First Article Inspection (eFAI) Reports for initial production builds will be available on request

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please acknowledge the receipt of the notice within 30 days of delivery. Lack of acknowledgement within 30 days constitutes acceptance of the change per JEDEC J-STD-046.

